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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Skala et al.	Examiner:	Im, J. M.
Serial No.:	09/874,606	Group Art Unit:	2811
Filed:	June 5, 2001	Docket No.:	New: PHA 51243A Old: (VLSI.282DIV1)
Title:	PAD METALIZATION OVER ACTIVE CIRCUITRY		

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on September 3, 2002.

By: [Signature]

Kelly Waltigney

OFFICE ACTION RESPONSE

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Please note the updated attorney docket number as listed above for this patent application (PHA 51243A), as part of the change of correspondence address and revocation of power of attorney documents previously filed. In response to the Office Action mailed June 5, 2002, please consider the following amendments and remarks.

In the Claims

Please amend claims 1, 11-12 and 14, and add new claims 15-20 as follows:

1. (Amended) A semiconductor chip having circuitry, the semiconductor chip comprising:
- a metal bond pad over the circuitry and insulated on at least two sides by passivation material;
  - a diffusion barrier layer over the metal bond pad, at least two entire sides of the diffusion layer being insulated by the passivation material; and
  - a metal layer over the circuitry, the metal bond pad, the diffusion barrier layer, and at least partially over, and in contact with, a portion of the passivation material not over the